

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_

PRODUCT 产品: \_\_\_\_\_ SAW FILTER \_\_\_\_\_

MODEL NO 型号: \_\_\_\_\_ HDBF08018A63 SF6-3 \_\_\_\_\_

PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_

APPROVED 批准: \_\_\_\_\_ D A T E 日期: \_\_\_\_\_ 2009-2-27 \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited



## 1. SCOPE

This specification shall cover the characteristics of SAW filter BF08018A63

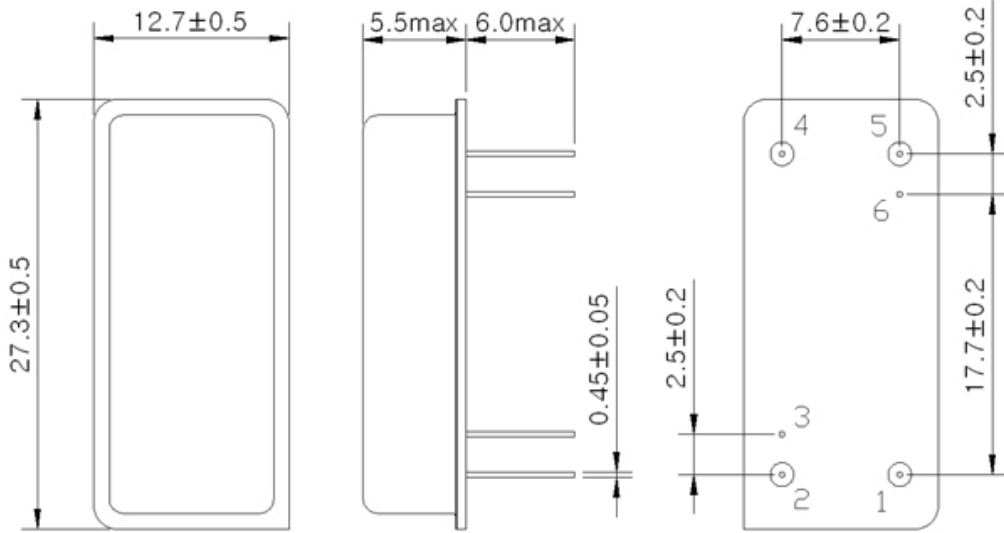
## 2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-40°C to +85°C
RF Power Dissipation	0dBm

### Electronic Characteristics

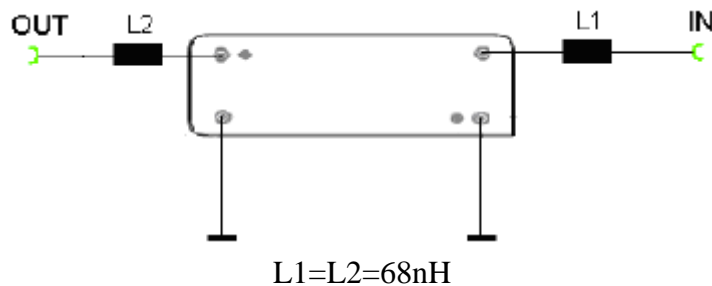
Parameter	Min	Typ	Max	Units
Center Frequency	79.90	80.00	80.10	MHz
Insertion Loss	-	28.5	30.0	dB
-1.5dB Bandwidth	18.0	18.18	-	MHz
-3dB Bandwidth	18.3	18.33	-	MHz
-35 dB Bandwidth	-	19.12	19.2	MHz
-40dB Bandwidth	-	19.2	19.4	MHz
Passband Variation		1.0	1.5	dB
Group Delay Variation	-	100	-	nsec
Absolute Delay	-	3.6	-	usec
Ultimate Rejection	-	48	-	dB
Substrate Material	YZ			
Ambient Temperature	25			°C

### 3. DIMENSION



Pin Configuration	
1	Input
5	Output
2, 4	Ground
Other	Case ground

### 4. TEST CIRCUIT



### 5. ENVIRONMENTAL CHARACTERISTICS

#### 5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in table 1.

**5-2 Low temperature exposure**

Subject the device to  $-20^{\circ}\text{C}$  for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in table 1.

**5-3 Temperature cycling**

Subject the device to a low temperature of  $-40^{\circ}\text{C}$  for 30 minutes. Following by a high temperature of  $+80^{\circ}\text{C}$  for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in table 1.

**5-4 Resistance to solder heat**

Dip the device terminals no closer than 1.5mm into the solder bath at  $260^{\circ}\text{C} \pm 10^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in table 1.

**5-5 Solderability**

Subject the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in table 1.

**5-6 Mechanical shock**

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in table 1.

**5-7 Vibration**

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in table 1.

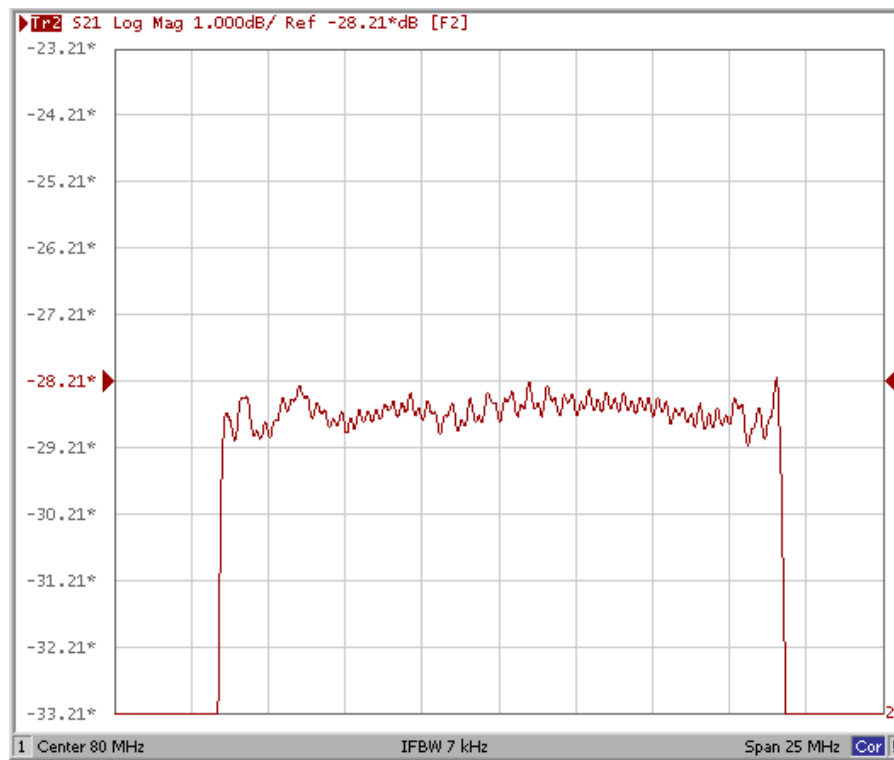
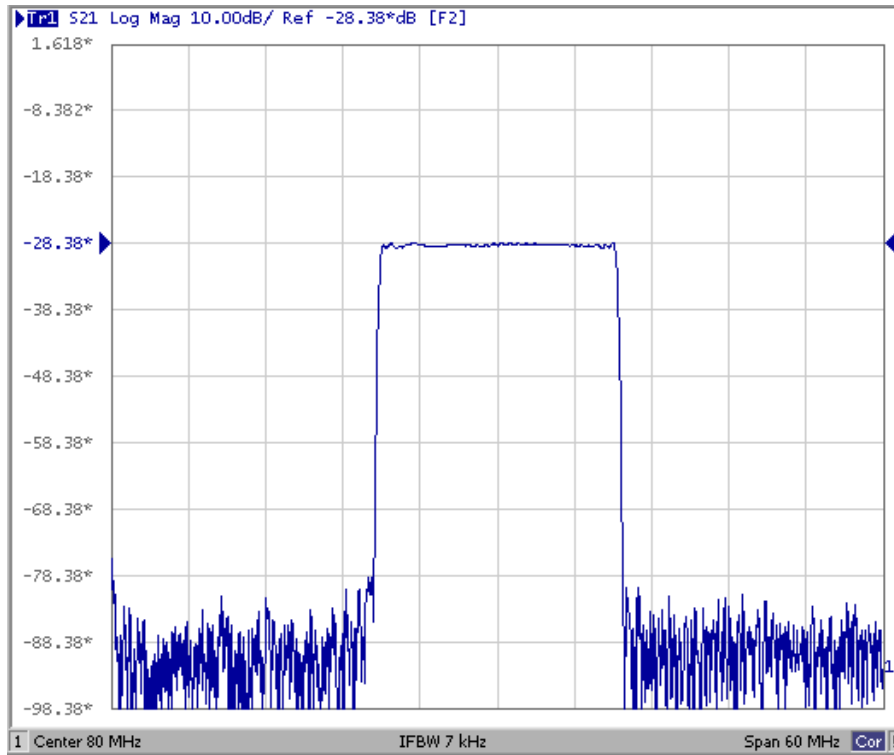
**5-8 Lead fatigue****5-8-1 Pulling test**

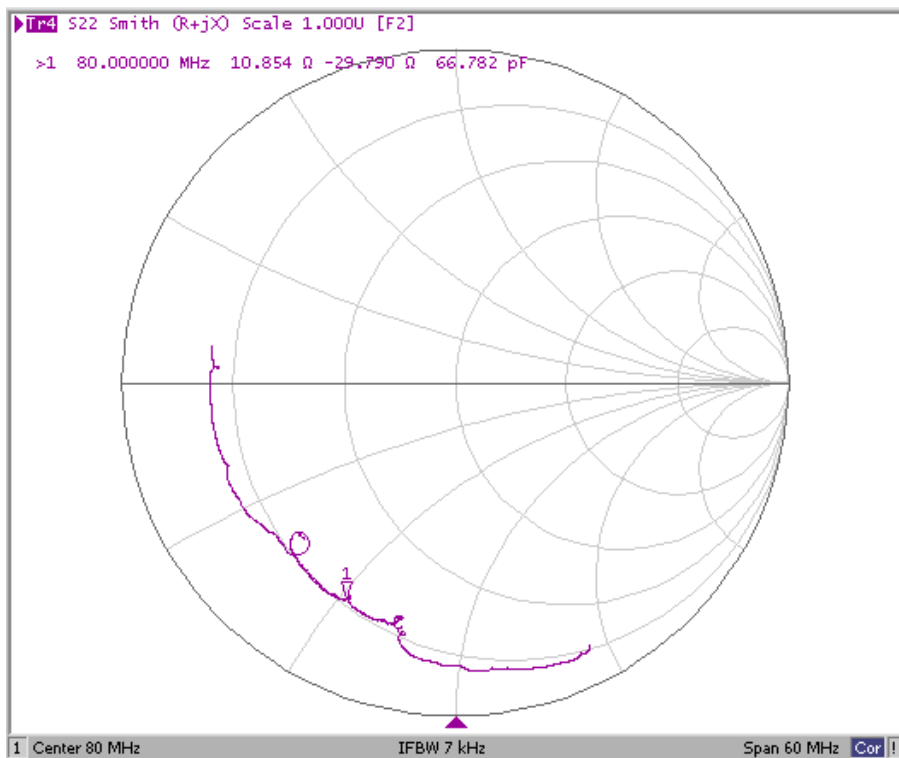
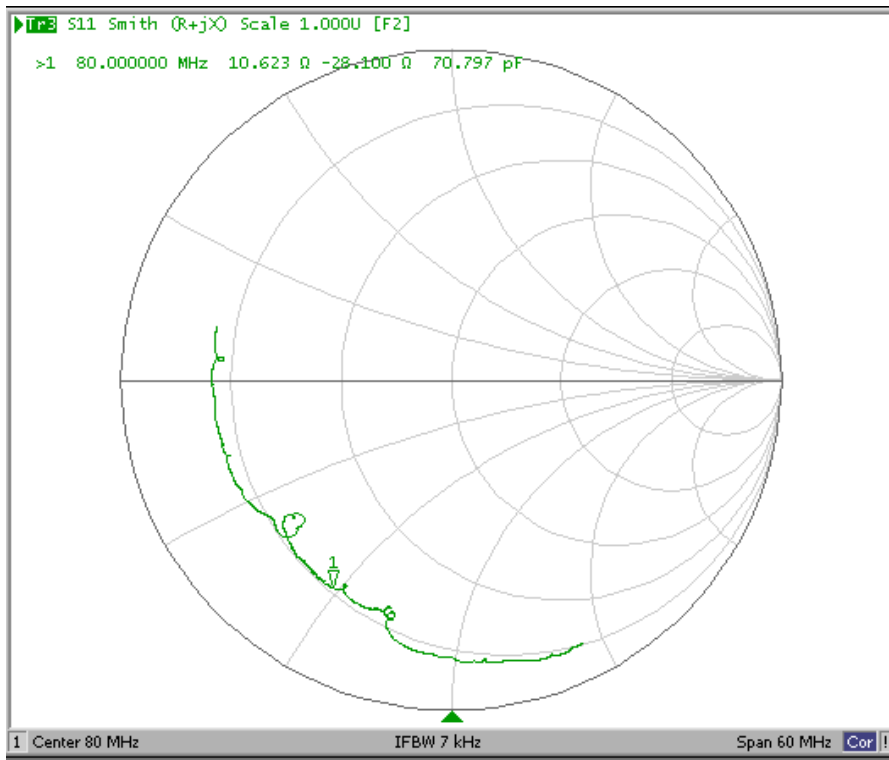
Weight along with the direction of lead without an shock 1kg. The device shall satisfy all the initial Characteristics.

**5-8-2 Bending test**

Lead shall be subject to withstand against  $90^{\circ}\text{C}$  bending with 450g weight in the direction of thickness. This operation shall be done toward both direction. The device shall show no evidence of damage and shall satisfy all the initial electrical characteristics.

## 6. Typical frequency response





## **7. REMARK**

### 7.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 7.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 7.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.